1l þ™1Q PC ™X ru1†qU! PC ˜˜ X xsYP … 2° B• • U FA4ƒ ™˜ I„Ptƒ! PC?"3FI•8" y& €… 4° ñ ù P f$d

电性参数

ǎ Ta=25 (ta=25)

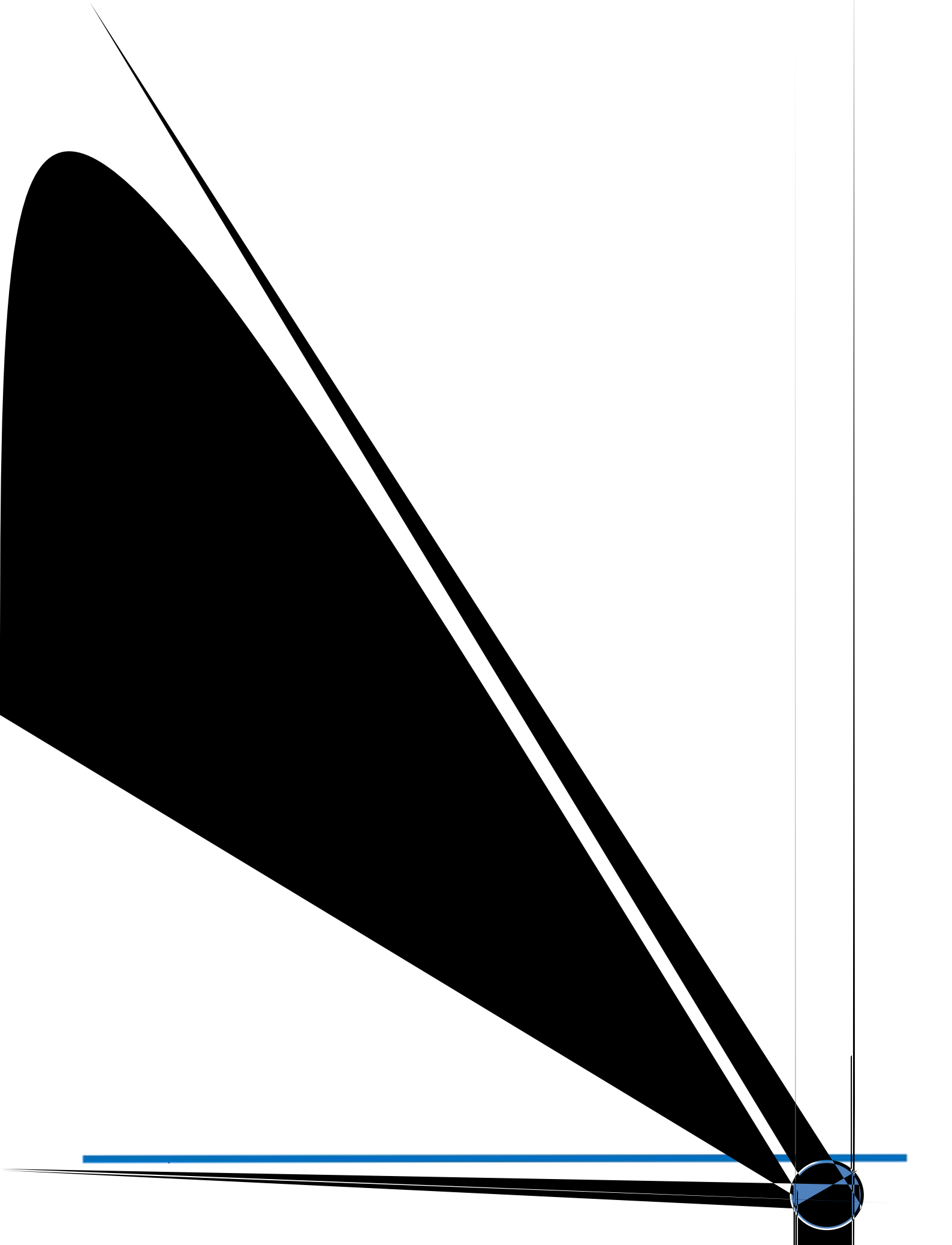
Item	Symbol	Absolute Maximum Ratig	Unit
w Power Dissipation	PD	15	W
h Forward Current	IF	1600	mA
h Pulse Forward Current	IFP	2000	mA
Operating Temperature	Topr	-40 TO +135	
Storage Temperature	Tstf	-40 TO +85	
Soldering Temperature	Tsld	Reflow Soldering:260 for 3sec	

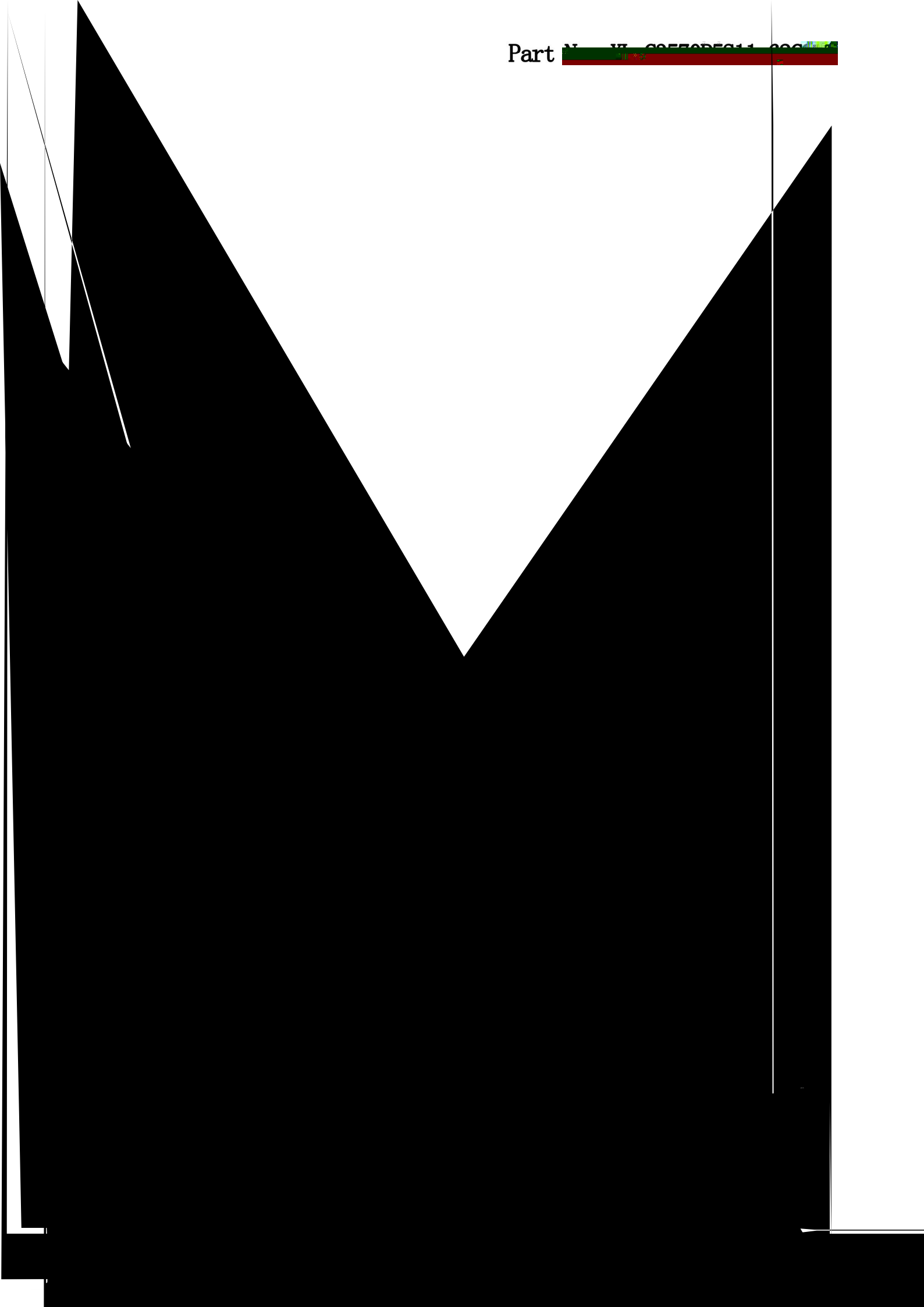
光电参数 Ta=25 (ta=25)

Parameter	Symbol	Condition	Value			Unit
			Min	Typ	Max	
Luminous flux	Φ	IF=1600mA	1600	-	2100	LM
h Forward Voltage	VF	IF=1600mA	8.7	-	9.6	V
color temperature	TC	IF=1600mA	5500	6500	7000	K
Color rendering index	RA	IF=1600mA	-	70	-	-
h Reverse Current	IR	-	-	-	-	uA
Viewing angle	2θ1/2	IF=1600mA	-	120	-	Deg
Thermal resistance Junction tempeu	Rthj-s	IF=1600mA	-	-	3-5	/W

5.

Part





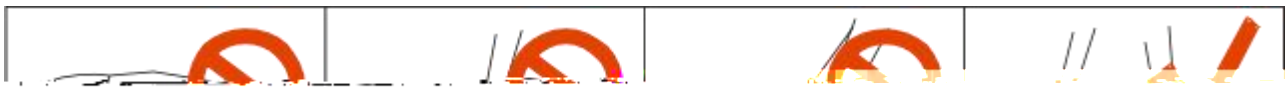
使用注意事项（3）

Precautions (3)

4. 其他事项

Others

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

5. 眼睛保护忠告：

Safety Advice For Human Eyes

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

If there are any modifications to the specification sheet, no further notice w e m " η ä